SDF369AB Epoxy Resin

Technical datasheet



Description & Application

SDF369AB is a solvent free type, modified high temperature resistant resin compound adhesive, used for hand paste molding and lamination molding, heating and curing, high hardness after curing, so it can withstand strong impact and vibration, has good mechanical properties and Insulation, can withstand temperature changes and flexing tearing stress, non-corrosive, widely used in the molding of composite materials such as carbon fiber, glass fiber, high temperature resistant composite board, mineral resin board and metal, ceramic, rubber, glass, fiber The reinforcement of products, etc., has excellent physical properties and high temperature resistance.

Product data

	Epoxy resin 369A	Harder 369B	Mixed Adhesive
Appearance	Transparent	Light yellow	
Specific gravity	1.08	1.02	
Viscosity at 25°C (Pa.s)	8000-10000	150-200	
Mixing Ratio (weight)	100	20	
Pot life at 25°C (100gr)			1.5h
Curing Conditions			2h at 100°C

Processing

- 1. Adhesive products need to be kept dry and clean; the workplace needs to be ventilated;
- 2. Please check Agent A before use, observe whether there is sedimentation, and stir Agent A well;
- 3. The amount is taken according to the proportion and the weighing is accurate. Please remember that the proportion is the weight ratio rather than the volume ratio. After the A and B agents are mixed, they must be stirred well to avoid incomplete curing;
- 4. First heat the resin to 40 °C (in winter)
- 5. Weigh accurately according to the ratio, stir evenly and stand still without bubbles.
- 6. Add the mixed liquid to the glue tank, keep the glue tank temperature above 20 °C for extrusion.
- 7. Very few people will have mild skin allergies and mild itching during prolonged contact with glue. It is recommended to wear protective gloves when using it. Please wipe it off with acetone or alcohol and clean it with a detergent.
- 8. Before using it in large quantities, please try it in a small amount to master the use skills of the product to avoid mistakes.

Typical cured properties

Hardness	Shore D	88 - 92
Tg temperature	$\mathscr C$	250
Heat resistance temperature	${\mathscr C}$	300
Withstand voltage	kv/mm	15-18
Compressive strength	Kg/mm2	20-25
Surface resistance	ohm	1.2×10 ¹⁴
Volume resistance	Ohm-cm	1×10 ¹⁵
Tensile strength	Kg/mm2	20-22
Shear strength	N/mm2	17
Water absorption rate	%	<0.03
Shrinkage	%	0.25-0.45

The above performance data are typical data measured in a laboratory environment with a temperature of 25 $^{\circ}$ C and a humidity of 70%, and are for customer reference only.